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[54] **METHOD OF DISPENSING FLUID ONTO A WAFER**

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[75] **Inventor:** **Soon E. Neoh, Singapore, Singapore**

[73] **Assignee:** **Chartered Semiconductor Manufacturing PTE Ltd., Singapore, Singapore**

Primary Examiner—Marion E. McCamish
Assistant Examiner—Laura Weiner
Attorney, Agent, or Firm—George O. Saile; Wolmar J. Stoffel

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[51] **Int. Cl.⁶** **G03C 5/00**

[52] **U.S. Cl.** **430/325; 430/326; 118/320**

[58] **Field of Search** **430/325, 326; 118/320**

[56] **References Cited**

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[57] **ABSTRACT**

A method for dispensing fluids on a semiconductor wafer wherein a wafer is mounted on a rotatable chunk, a fluid to be dispensed is introduced into a well through an inlet located adjacent the bottom of the well, rotating the chunk and moving a soft impact dispensing nozzle, that draws bubble-free fluid from the bottom of the well, over the wafer, and dispensing the fluid at a low pressure and a short distance to the wafer surface.

8 Claims, 4 Drawing Sheets